

## SPECIFICATIONS

## MXM 3.0 Socket

### Mechanical

**Contact Retention Force:** 0.10kg min.

**Durability :** 25 Cycles

### Electrical

**Voltage Rating:** 25V

**Current Rating:** 0.5A

**Contact Resistance:** 55mΩ max.

**Dielectric Withstanding Voltage:** 200V AC/1 min.

**Insulation Resistance:** 100MΩ

### Physical

**Housing:** Thermoplastic, UL 94V-0 rated in Ivory Color

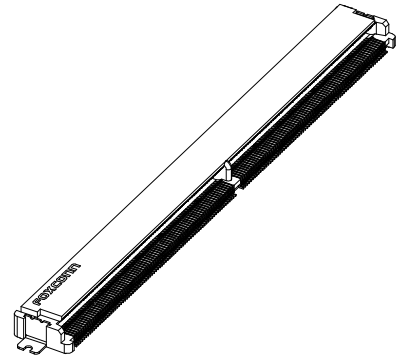
**Contact:** Copper alloy

**Plating:** See "ORDERING INFORMATION"

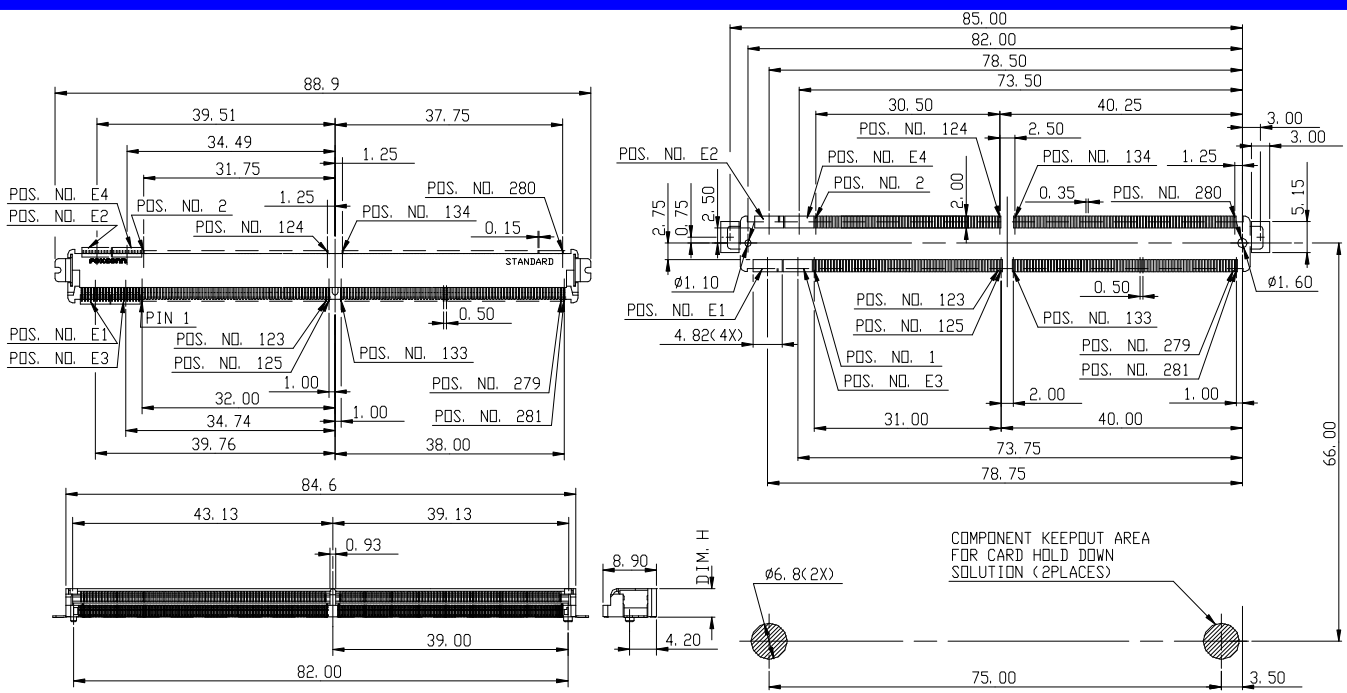
**Metal Spring:** Copper alloy

**Operating Temperature:** -55℃ to +85℃

**AS Series**  
**4.3mm&5.5mm&**  
**7.8mm Height**  
**SMT Type**  
**0.50mm Pitch**  
**314 Pos.**



## DRAWING



RECOMMENDED PCB LAYOUT

## ORDERING INFORMATION

PRODUCT NO.: **AS0B82\*-S\*\*B-\*H**

Memory Module Socket

Horizontal Type

Single Row

No. of Pos.

B8=314Pos.

SMT Type

Contact Area Plating

1=Gold Flash

6=10u" Gold plating

H=Halogen/Lead Free

Package Code

4=Soft Tray

7=Carrier tape

B=Black Color

43=4.3mm Height

55=5.5mm Height

78=7.8mm Height

S=Standard Type

|                 |        |
|-----------------|--------|
| AS0B82*-S43B-*H | 4.3    |
| AS0B82*-S55B-*H | 5.5    |
| AS0B82*-S78B-*H | 7.8    |
| P/N             | DIM. H |